

## MRI150.12F

### 2 in 1 Fast IGBT Modules

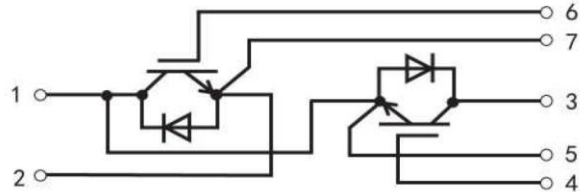


#### Features:

- Low switching losses
- Low inductance
- Fast switching and short tail current
- High power and thermal cycling capability
- Al<sub>2</sub>O<sub>3</sub> substrate with low thermal resistance
- Copper base plate

#### Typical applications:

- High frequency switching application
- Motor drives
- UPS system



Symbol	Characteristics	Test Conditions	Value			Unit
			Min	Typ	Max	
<b>• IGBT, Inverter</b>						
V <sub>CEs</sub>	Collector-Emitter voltage	T <sub>j</sub> = 25°C			1200	V
V <sub>GES</sub>	Gate-Emitter voltage				±20	V
I <sub>C</sub>	Collector current	Continuous @ T <sub>c</sub> = 25 °C, Tvj max = 175°C			238	A
		Continuous @ T <sub>c</sub> = 100 °C, Tvj max = 175°C			150	A
I <sub>CRM</sub>	Repetitive peak collector current	T <sub>p</sub> = 1 ms			300	A
P <sub>tot</sub>	Power dissipation per IGBT	T <sub>C</sub> = 25°C, T <sub>j</sub> = 175°C			1000	W
T <sub>jmax</sub>	Max junction temperature				175	°C
T <sub>j</sub>	Operating temperature		-40		150	°C
T <sub>stg</sub>	Storage temperature		-40		125	°C
V <sub>ISO</sub>	Isolation terminal/copper base	AC: 1 minute			3000	V
Screw torque	Mounting (M6)		3.0		5.0	N·m
	Terminals (M5)		2.5		5.0	N·m
I <sub>CEs</sub>	Zero gate voltage collector current	T <sub>j</sub> = 25°C, V <sub>CE</sub> = 1200V, V <sub>GE</sub> = 0V			1	mA
		T <sub>j</sub> = 150°C, V <sub>CE</sub> = 1200V, V <sub>GE</sub> = 0V			5	mA
I <sub>GES</sub>	Gate-Emitter leakage current	T <sub>j</sub> = 25°C, V <sub>CE</sub> = 0V, V <sub>GE</sub> = ±20V	-400		400	nA
V <sub>GE(th)</sub>	Gate-Emitter threshold voltage	T <sub>j</sub> = 25°C, V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 8mA	5.2	6.0	6.5	V
V <sub>CE(sat)</sub>	Collector-Emitter saturation voltage	T <sub>j</sub> = 25°C, V <sub>GE</sub> = 15V, I <sub>C</sub> = 150A		2.0	2.4	V
		T <sub>j</sub> = 125°C, V <sub>GE</sub> = 15V, I <sub>C</sub> = 150A		2.25		V
		T <sub>j</sub> = 150°C, V <sub>GE</sub> = 15V, I <sub>C</sub> = 150A		2.35		V
C <sub>ies</sub>	Input capacitance	T <sub>j</sub> = 25°C, V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz		15.6		nF
C <sub>res</sub>	Reverse transfer capacitance	T <sub>j</sub> = 25°C, V <sub>CE</sub> = 25V, V <sub>GE</sub> = 0V, f = 1MHz		600		pF
Q <sub>g</sub>	Gate charge	V <sub>CE</sub> = 600V, I <sub>C</sub> = 150A, V <sub>GE</sub> = 15V		0.95		µC
R <sub>Gint</sub>	Internal gate resistor	T <sub>j</sub> = 25°C		2.5		Ω
t <sub>d,on</sub>	Turn-on time	V <sub>CE</sub> = 600V, I <sub>C</sub> = 150A, V <sub>GE</sub> = ±15V, R <sub>G</sub> = 5.1Ω, inductive load	T <sub>j</sub> = 25°C		160	ns
			T <sub>j</sub> = 125°C		170	ns
			T <sub>j</sub> = 150°C		180	ns
t <sub>r</sub>	Rise time	V <sub>CE</sub> = 600V, I <sub>C</sub> = 150A, V <sub>GE</sub> = ±15V, R <sub>G</sub> = 5.1Ω, inductive load	T <sub>j</sub> = 25°C		60	ns
			T <sub>j</sub> = 125°C		65	ns
			T <sub>j</sub> = 150°C		65	ns

Symbol	Characteristics	Test Conditions	Value			Unit
			Min	Typ	Max	
$t_{d,off}$	Turn-off time	$V_{CE} = 600V, I_C = 150A,$ $V_{GE} = \pm 15V, R_G = 4.1\Omega, \text{ inductive load}$	$T_j = 25^\circ C$	400		ns
			$T_j = 125^\circ C$	450		ns
			$T_j = 150^\circ C$	460		ns
$t_f$	Fall time	$V_{CE} = 600V, I_C = 150A,$ $V_{GE} = \pm 15V, R_G = 4.1\Omega, \text{ inductive load}$	$T_j = 25^\circ C$	50		ns
			$T_j = 125^\circ C$	55		ns
			$T_j = 150^\circ C$	55		ns
$E_{on}$	Turn-on energy loss per pulse	$V_{CE} = 600V, I_C = 150A,$ $V_{GE} = \pm 15V, R_G = 5.1\Omega, \text{ inductive load}$	$T_j = 125^\circ C$	21.5		mJ
			$T_j = 150^\circ C$	24		mJ
$E_{off}$	Turn-off energy loss per pulse	$V_{CE} = 600V, I_C = 150A,$ $V_{GE} = \pm 15V, R_G = 5.1\Omega, \text{ inductive load}$	$T_j = 125^\circ C$	7.3		mJ
			$T_j = 150^\circ C$	7.7		mJ
$I_{sc}$	SC data	$V_{GE} = 15V, V_{CC} = 600V, T_j = 150^\circ C,$ $10\mu s$	$tpsc \leq$	900		A
$R_{th(j-c)}$	Thermal resistance, junction to case	Per IGBT			0.15	$^\circ C/W$
<b>• Diode, Inverter</b>						
$V_{RRM}$	Repetitive peak reverse voltage	$T_j = 25^\circ C$			1200	V
$I_F$	Forward current	Continuous			150	A
$I_{FRM}$	Repetitive peak forward current	$T_p = 1ms$			300	A
$I^2t$		$T_j = 125^\circ C, t = 10ms, V_R = 0V$			3200	$A^2s$
$V_F$	Forward voltage	$V_{GE} = 0V, I_F = 150A$	$T_j = 25^\circ C$	2.0	2.5	V
			$T_j = 125^\circ C$	2.05		V
			$T_j = 150^\circ C$	2.05		V
$t_{rr}$	Reverse recovery time	$V_R = 600V, I_F = 150A,$ $1900A/\mu s, T_j = 150^\circ C$	$di_F/dt =$		140	ns
$I_{RRM}$	Max reverse recovery current				119	A
$Q_{RR}$	Reverse recovery charge				14.6	$\mu C$
$E_{rec}$	Reverse recovery energy				4.7	mJ
$R_{th(JCD)}$	Thermal resistance, junction to case	Per diode			0.30	$^\circ C/W$
$W_t$	Weight			160		g

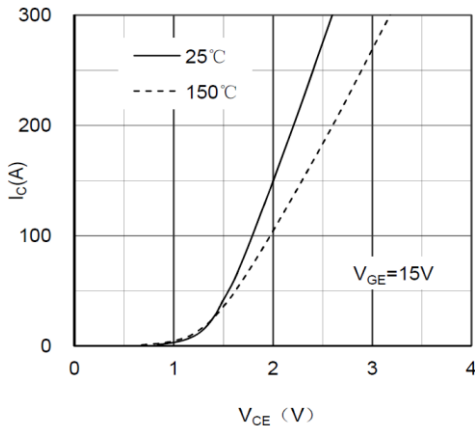


Figure 1. Typical Output Characteristics IGBT-inverter

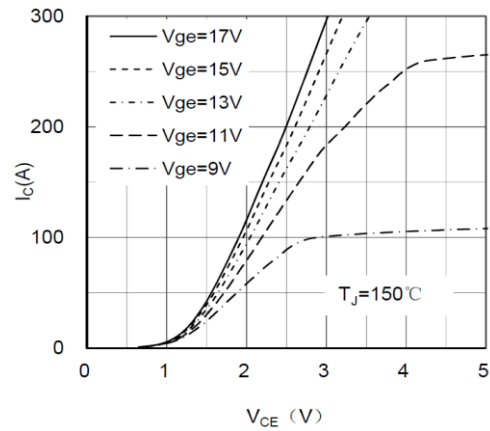


Figure 2. Typical Output Characteristics IGBT-inverter

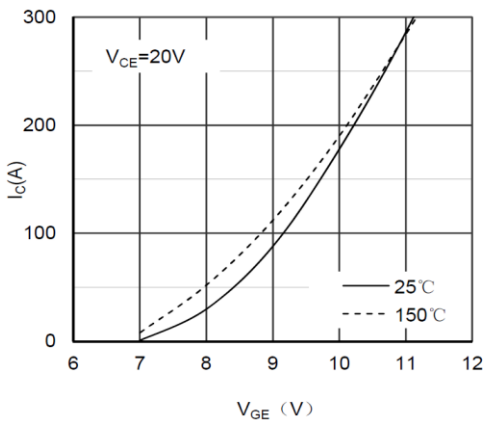


Figure 3. Typical Transfer characteristics IGBT-inverter

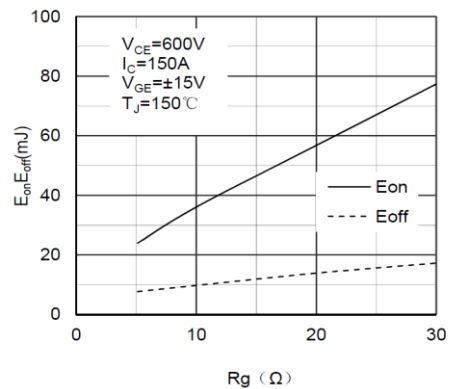


Figure 4. Switching Energy vs Gate Resistor IGBT-inverter

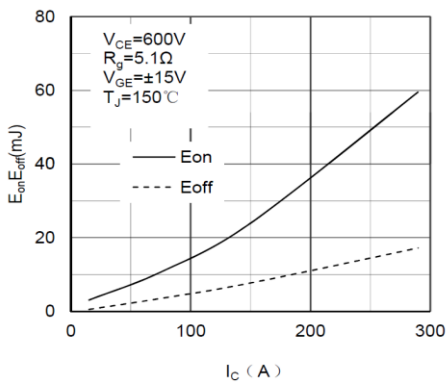


Figure 5. Switching Energy vs Collector Current IGBT-inverter

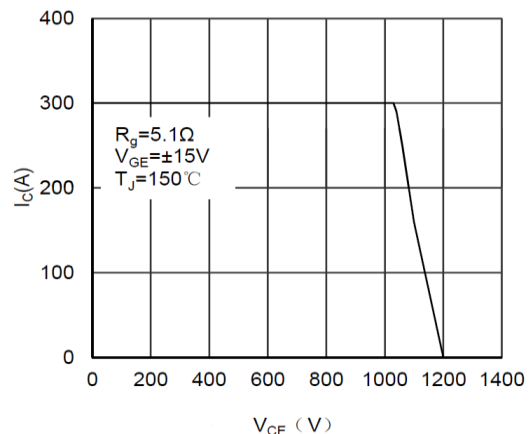


Figure 6. Reverse Biased Safe Operating Area IGBT-inverter

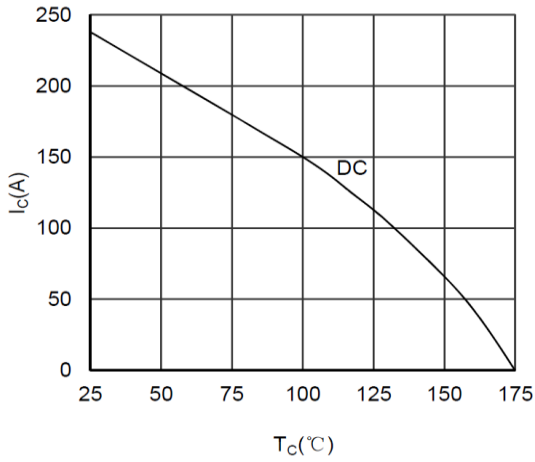


Figure 7. Collector Current vs Case temperature IGBT -inverter

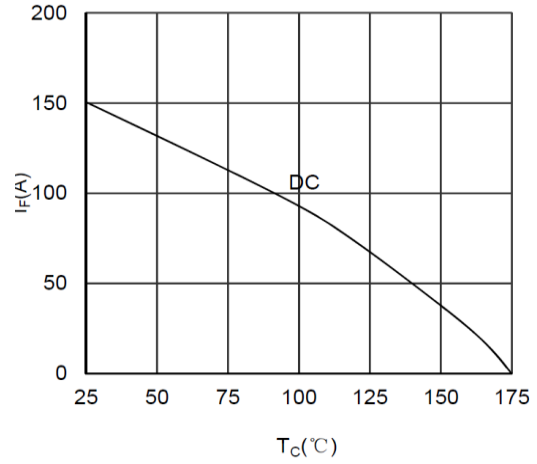


Figure 8. Forward current vs Case temperature Diode -inverter

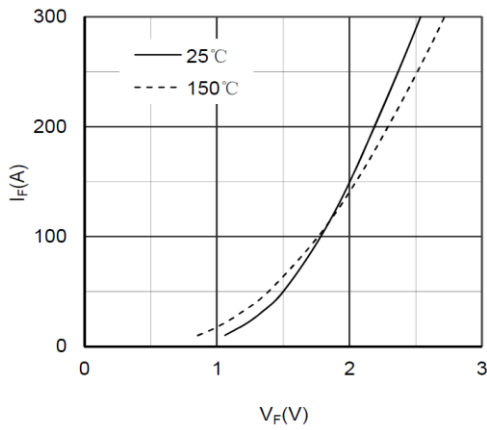


Figure 9. Diode Forward Characteristics Diode -inverter

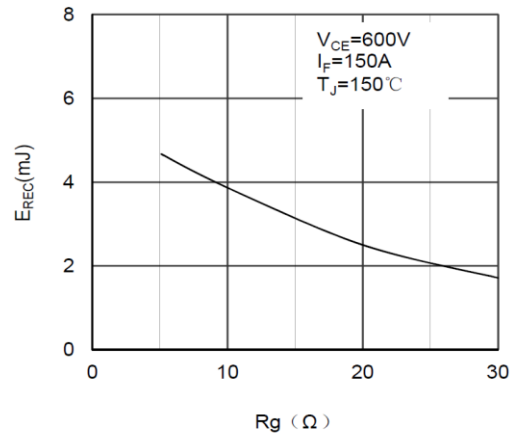


Figure 10. Switching Energy vs Gate Resistor Diode -inverter

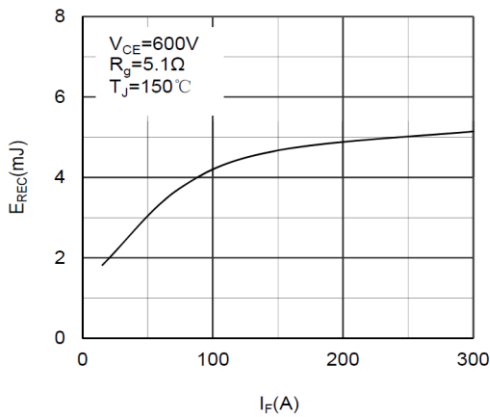


Figure 11. Switching Energy vs Forward Current Diode-inverter

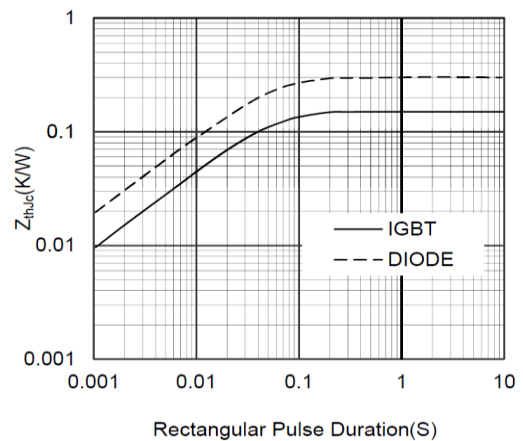
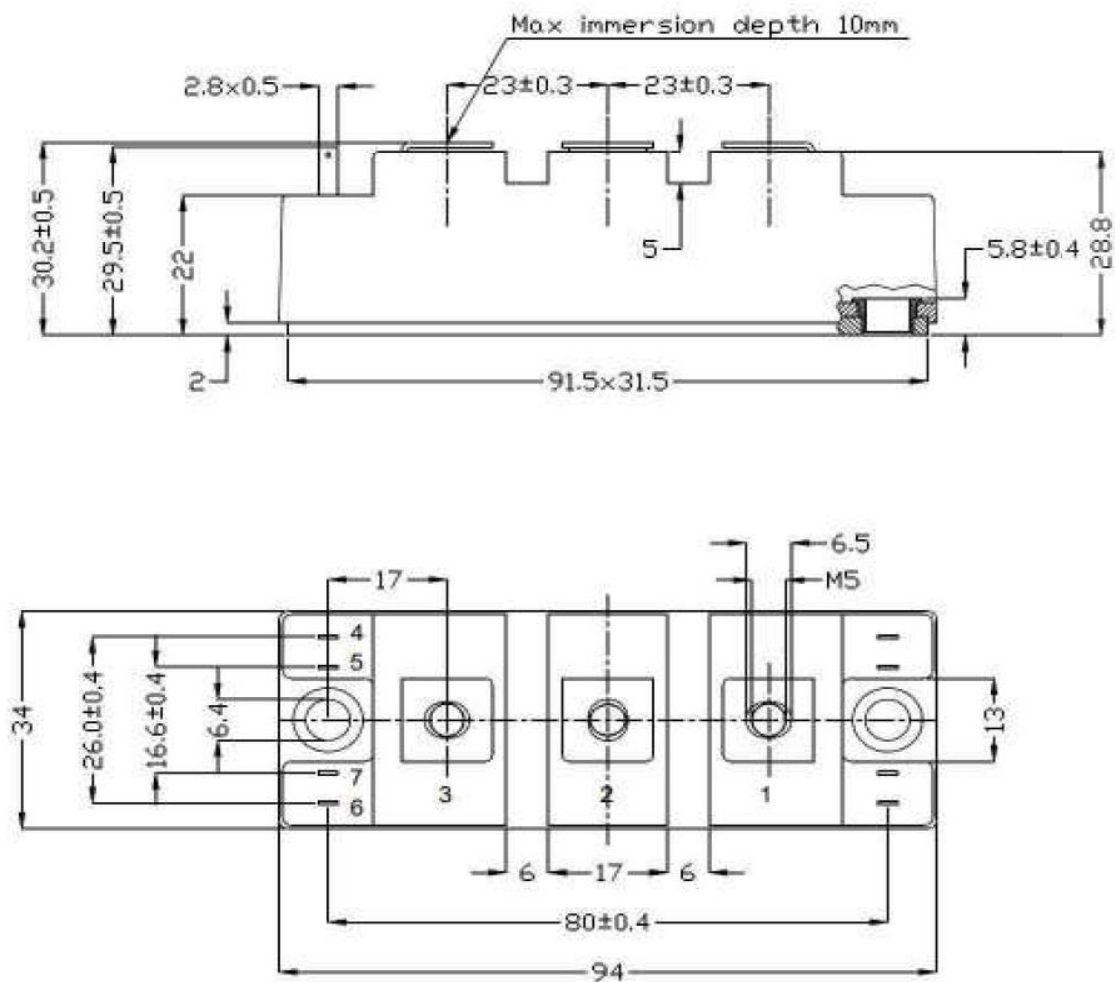


Figure 12. Transient Thermal Impedance of Diode and IGBT-inverter

### Outline:



(dimensions in mm)

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